

Team Meetings

| Date: | Duration: | Purpose of Meeting: | Items Discussed: |
|------------|-----------|--|---|
| 9/10/2013 | 30 mins | Team formation and course expectations | Team member contract and group email formed |
| 9/23/2013 | 15 mins | Meeting with Joseph White to discuss solder types | Bond formations, SEL practices |
| 9/26/2013 | 45 mins | Investigate on campus resources, project head expectations | Stacked solder joint reliability issues, thermal-cycling tests, industry standards in solder testing, clean room access, FEA software, client interviews |
| 10/11/2013 | 30 mins | Prepare for Snapshot and client interview, on-campus resources | Established meeting time and supplies needed for posterboard, construct Gantt chart, how to obtain clean room access, contact Dominin Nwoye about clean room access |
| 10/12/2013 | 30 mins | Work on Snapshot board, create project Gantt chart | Found visual aid pictures, planned out data collection timeline |
| 10/14/2013 | 45 mins | Client phone conference | Met Owen Faye and discussed project scope, introduced to 5 SAC types and 4 surface finishes, expectations of component FEA model |
| 10/17/2013 | 1.5 hours | Clean room usage with Dominic Nwoye | Learned about available lab equipment and basic functions of each, practiced using braze to bond silica dyes |
| 10/18/2013 | 45 mins | Project details discussion and FEA modeling options | Begin creating wiki page, usage of Abaqus to model thermal cycling, reviewing of client information, |
| 10/22/2013 | 1.5 hours | Design proposal formulation | Discussed proposal objectives, hypothesis, methodology, statistical method |
| 10/23/2013 | 30 mins | Clean room equipment check for reporting info | Gathered data for machines containing serial #'s, manufacturer, reporting accuracy, tolerances |
| 10/25/2013 | 20 mins | Weekly team meeting | Jose mentioned FEA testing needs, discussed purchasing solder, type of solder feed into campus machinery, collected details on PCB configuration |